

# SOD323 Plastic-Encapsulate Diodes

**Schottky Rectifier**

## Features

- $I_o$  0.35A
- V<sub>RRM</sub> 20V-40V
- High surge current capability
- Low Forward Voltage

**SOD323**



## Marking

SD103AWS:S4 SD103BWS:S5 SD103CWS:S6

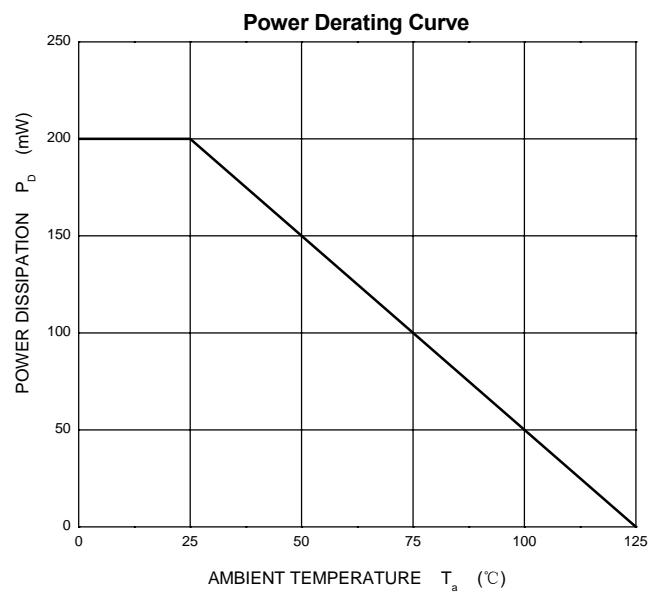
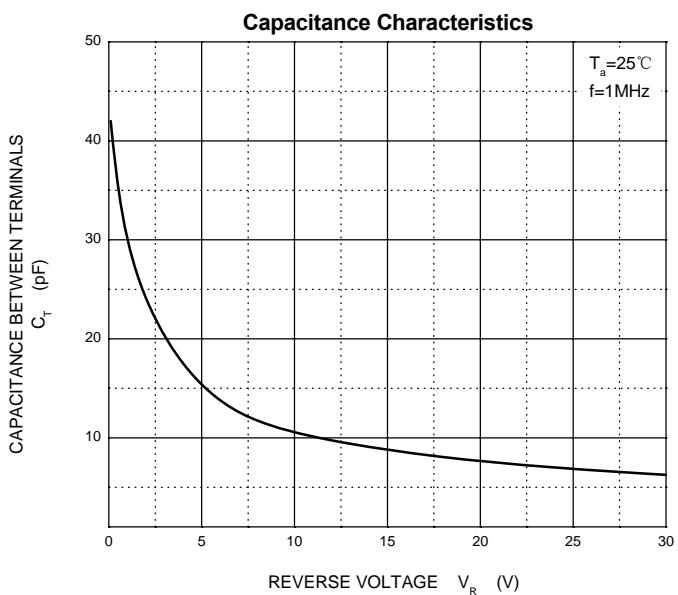
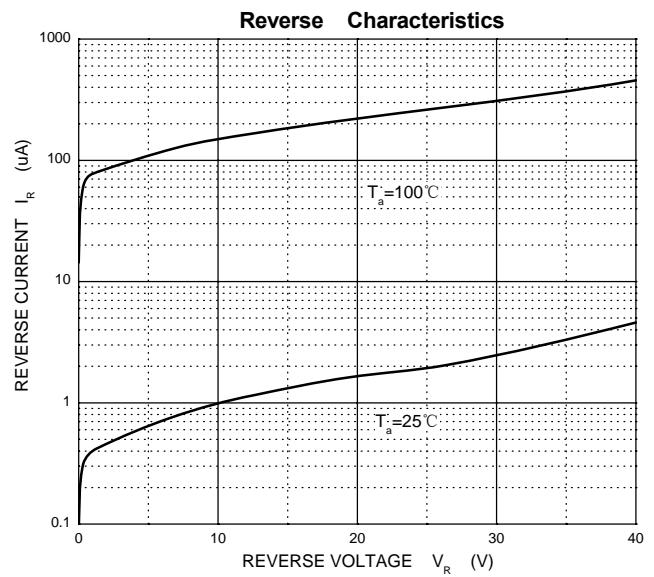
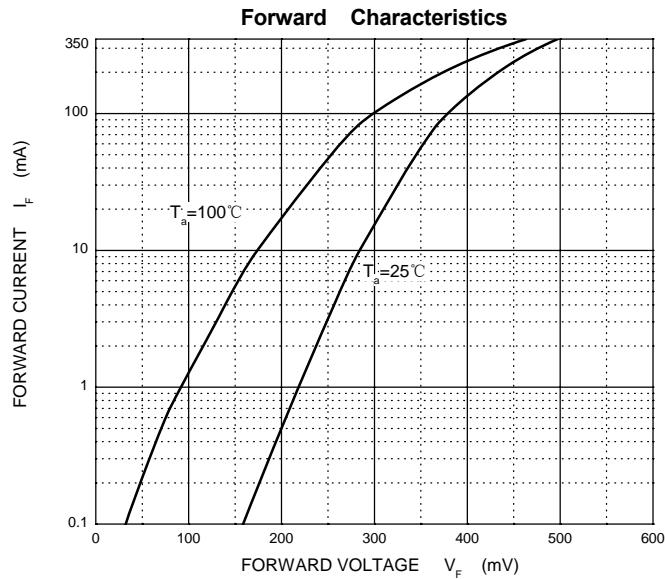
## Limiting Values (Absolute Maximum Rating)

Parameter	Symbol	SD103AWS	SD103BWS	SD103CWS	Unit
Peak Repetitive Peak Reverse Voltage	V <sub>RRM</sub>				
Working Peak Reverse Voltage	V <sub>RWM</sub>	40	30	20	V
DC Blocking Voltage	V <sub>R</sub>				
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	21	14	V
Forward Continuous Current	I <sub>FM</sub>		350		mA
Bcbl!fepetitive Peak Forward Surge Current @t1, " a s	I <sub>FSM</sub>		2.0		A
Power Dissipation	P <sub>d</sub>		200		mW
Thermal Resistance Junction to Ambient	R <sub>θJA</sub>		500		°C/W
Junction Temperature	T <sub>j</sub>		125		°C
Storage Temperature	T <sub>STG</sub>		-55~+150		°C

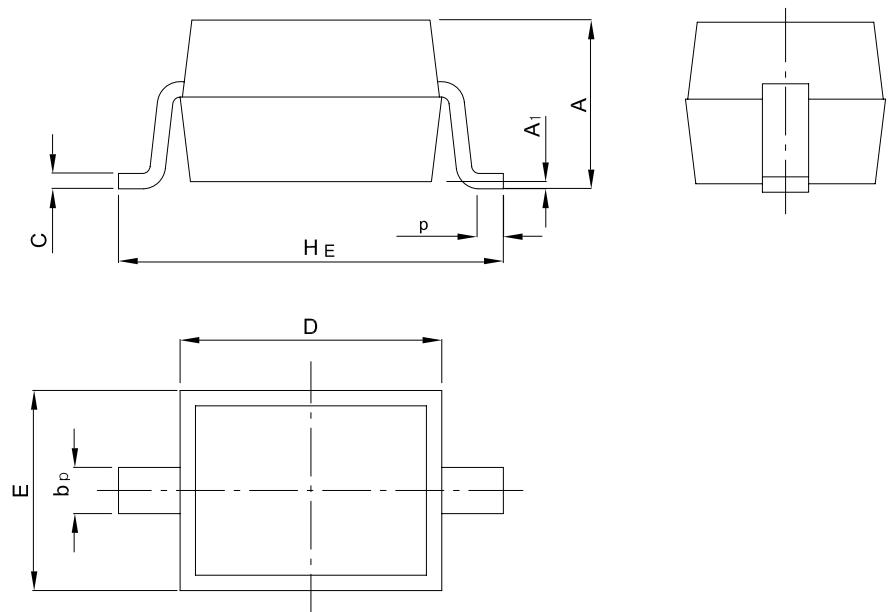
## Electrical Characteristics (T<sub>a</sub>=25°C Unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Reverse breakdown voltage SD103AWS SD103BWS SD103CWS	V <sub>(BR)</sub>	40 30 20			V	I <sub>R</sub> =100µA I <sub>R</sub> =100µA I <sub>R</sub> =100µA
Forward voltage	V <sub>F</sub>			0.37 0.60	V	I <sub>F</sub> =20mA I <sub>F</sub> =200mA
Reverse current SD103AWS SD103BWS SD103CWS	I <sub>RM</sub>			5.0	µA	V <sub>R</sub> =30V V <sub>R</sub> =20V V <sub>R</sub> =10V
Capacitance between terminals	C <sub>T</sub>			50	pF	V <sub>R</sub> =0V,f=1.0MHz
Reverse recovery time	t <sub>rr</sub>		10		ns	I <sub>F</sub> =I <sub>R</sub> =200mA I <sub>rr</sub> =0.1XI <sub>R</sub> ,R <sub>L</sub> =100Ω

## Typical Characteristics

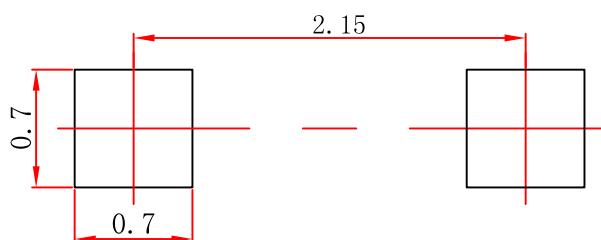


## SOD323 Package Outline Dimensions



UNIT	A	b <sub>p</sub>	C	D	E	H <sub>E</sub>	A <sub>1</sub>	L <sub>p</sub>
mm	1.20 0.80	0.40 0.25	0.15 0.10	1.80 1.60	1.35 1.15	2.80 2.30	0.10 0.01	0.50 0.20

## SOD323 Suggested Pad Layout



### Note:

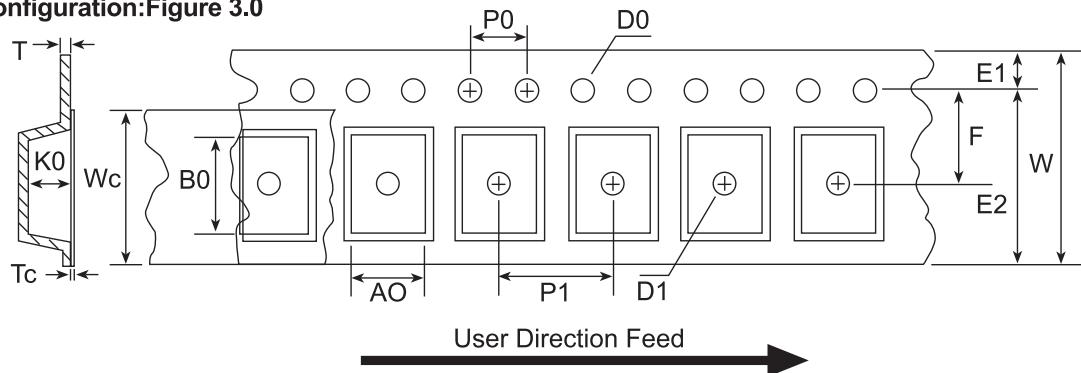
1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$  mm.
3. The pad layout is for reference purposes only.

### NOTICE

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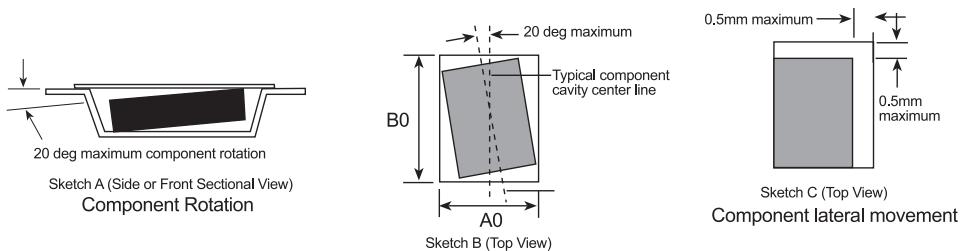
# Reel Taping Specifications For Surface Mount Devices-SOD323

**SOD323 Embossed Carrier Tape Configuration:Figure 3.0**

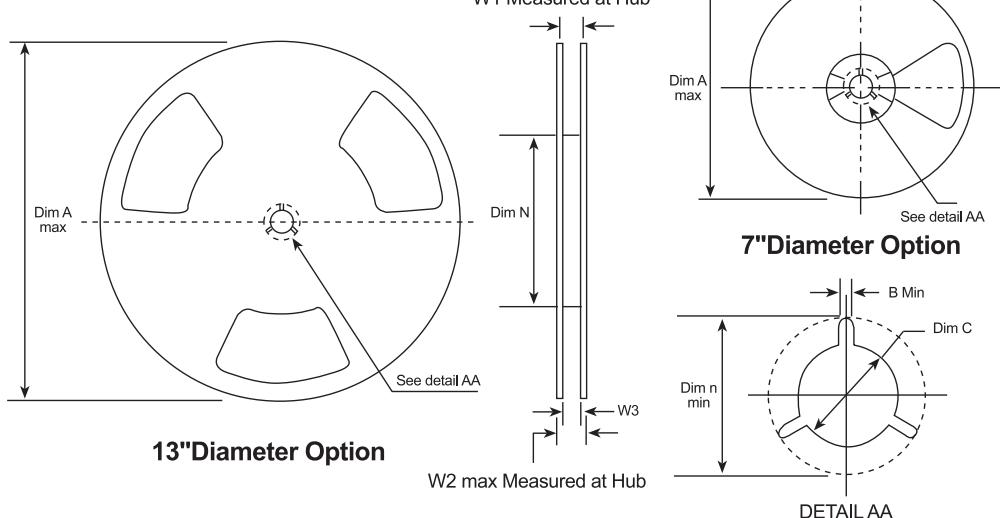


Dimensions are millimeter														
Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SOD323 (8mm)	1.46 +/-0.10	2.9 +/-0.10	8.0 +/-0.3	1.50 +/-0.125	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.10	4.0 +/-0.10	1.25 +/-0.10	0.25 +/-0.020	5.2 +/-0.20	0.06 +/-0.02

Notes:A0,B0 and K0 dimensions are determined with respect to the EW Jedecl RS-481 rotational and lateral movement requirements (see sketches A,B and C).



**SOD323 Reel Configuration:Figure 4.0**



Dimensions are in inches and millimeter									
Type Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512+0.020/-0.008 13+0.5/-0.2	0.795 20.0	2.165 55	0.331+0.059/-0.000 8.4+1.5/0	0.567 14.4	0.311-0.429 7.9-10.9
8mm	13" Dia	13.00 330	0.059 1.5	512+0.020/-0.008 13+0.5/-0.2	0.795 20.0	4.00 100	0.331+0.059/-0.000 8.4+1.5/0	0.567 14.4	0.311-0.429 7.9-10.9